

ROBOTHERM

Robotics and Thermal Process Solution for Electronics Assembly,
Semiconductor Packaging and Engineered Products industries



MATERIAL HANDLING SYSTEM

WORHOLDER / INDEXER SERIES

Automatic X-Y-Theta Table Model

APPLICATIONS

Working Area Extension

- Hybrid Bonding
- Stitch Bonding
- Die Attach
- Bumping
- Encapsulation

OEM Equipments Upgrading

- Ball Bonder
- Wedge Bonder
- Die Bonder
- Encapsulation

STANDARD FEATURES & BENEFITS

X Axis stroke, 150 mm

Y Axis stroke, 70 mm

Theta Motion, 270°

Workholder

- Vacuum hold down and/or clamping
- Heated or cold block

Software Controlled Parameters

- 3 axes control board
- Indexing sequences
- Index pitch
- Acceleration, speed, deceleration
- XYTheta coordinate

Acceleration : 0,01 à 2 G

Speed : up to 2 m/s

Stable and Reproducible process

Resolution 0,5 μ m

RS 232 Communications

Cleanroom Compatible

Optimal accessibility for service and maintenance
Durable low maintenance design for maximum "uptime"

Common European (CE) Product Safety Certification
SMEMA Compliant

In Robotherm's policy for continuous improvement, specifications can change without prior notice